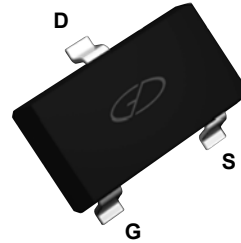
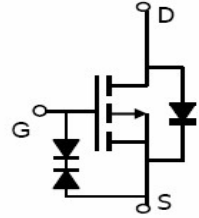


Main Product Characteristics

BV_{DSS}	-20V
$R_{DS(ON)}$	45m Ω
I_D	-4A



SOT23



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSF3415B utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current-Continuous	I_D	-4	A
Drain Current-Pulsed ¹	I_{DM}	-30	A
Maximum Power Dissipation	P_D	1.4	W
Thermal Resistance, Junction-to-Ambient ²	$R_{\theta JA}$	89.3	$^{\circ}C/W$
Storage Temperature Range	T_{STG}	-55 To +150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 To +150	$^{\circ}C$

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-20	-	-	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$	-	-	1	μA
Gate-Source Leakage Current	I_{GSS1}	$V_{GS}=\pm 8V, V_{DS}=0V$	-	± 0.7	± 5	μA
Gate-Source Leakage Current	I_{GSS2}	$V_{GS}=\pm 10V, V_{DS}=0V$	-	± 2.1	± 10	μA
On Characteristics³						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.35	-0.55	-0.9	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-4A$	-	34	45	m Ω
		$V_{GS}=-2.5V, I_D=-4A$	-	44	60	
		$V_{GS}=-1.8V, I_D=-1A$	-	46	65	
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_D=-4A$	8	-	-	S
Dynamic Characteristics⁴						
Input Capacitance	C_{iss}	$V_{DS}=-10V, V_{GS}=0V, F=1MHz$	-	950	-	pF
Output Capacitance	C_{oss}		-	165	-	
Reverse Transfer Capacitance	C_{rss}		-	120	-	
Switching Characteristics⁴						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=-10V, R_L=2.5\Omega, V_{GS}=-4.5V, R_{GEN}=3\Omega$	-	12	-	nS
Turn-On Rise Time	t_r		-	10	-	
Turn-Off Delay Time	$t_{d(off)}$		-	19	-	
Turn-Off Fall Time	t_f		-	25	-	
Total Gate Charge	Q_g	$V_{DS}=-10V, I_D=-4A, V_{GS}=-4.5V$	-	12	-	nC
Gate-Source Charge	Q_{gs}		-	1.4	-	
Gate-Drain Charge	Q_{gd}		-	3.6	-	
Drain-Source Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	$V_{GS}=0V, I_S=-4A$	-	-	-1.2	V
Diode Forward Current ²	I_S		-	-	-4	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristic Curves

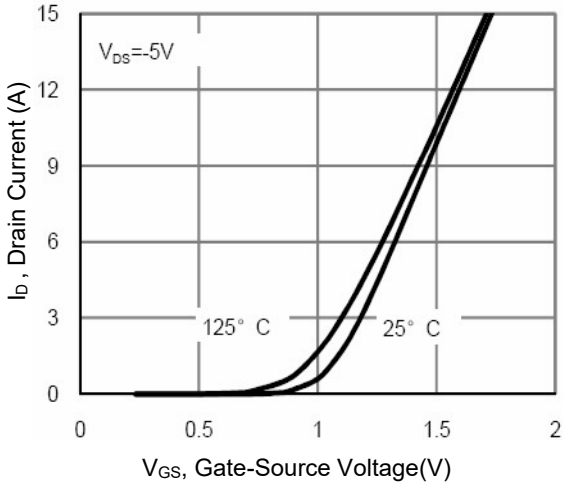


Figure 1. Transfer Characteristics

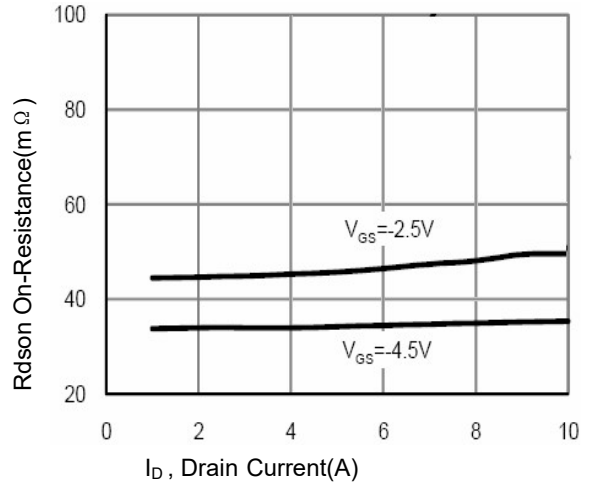


Figure 2. Drain-Source On-Resistance

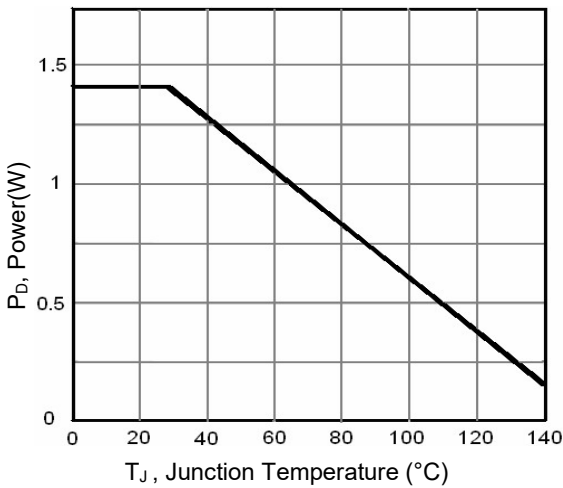


Figure 3. Power Dissipation

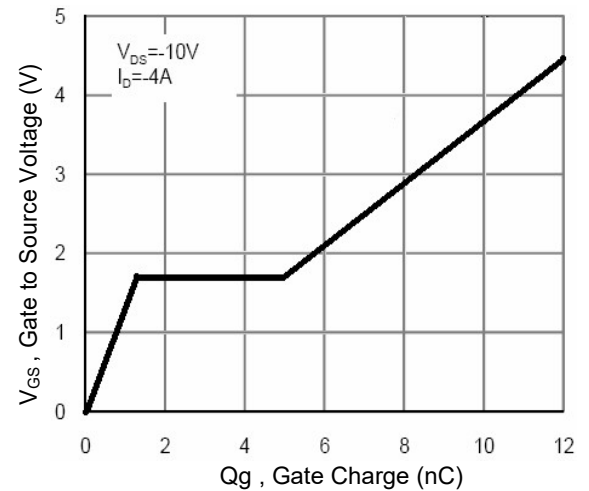


Figure 4. Gate Charge

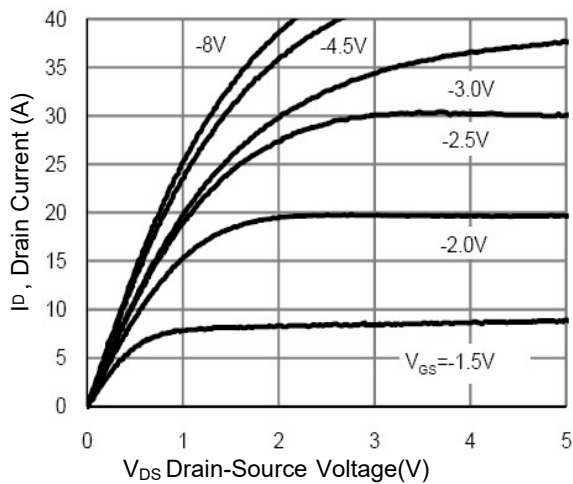


Figure 5. Output Characteristics

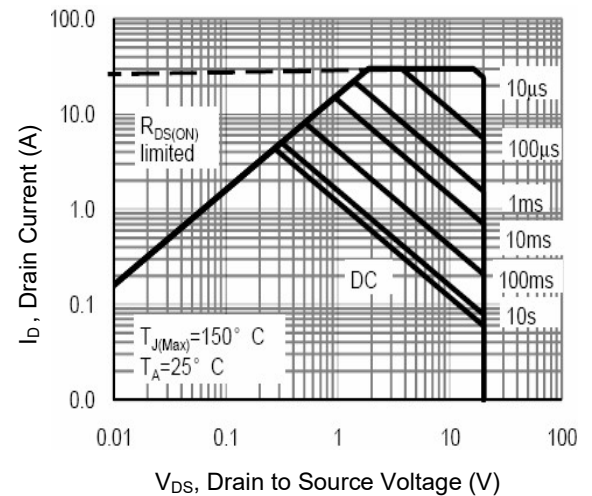


Figure 6. Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

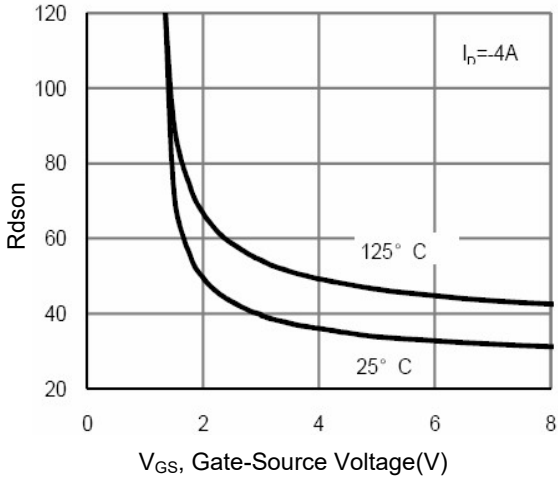


Figure 7. Rdson vs. VGS

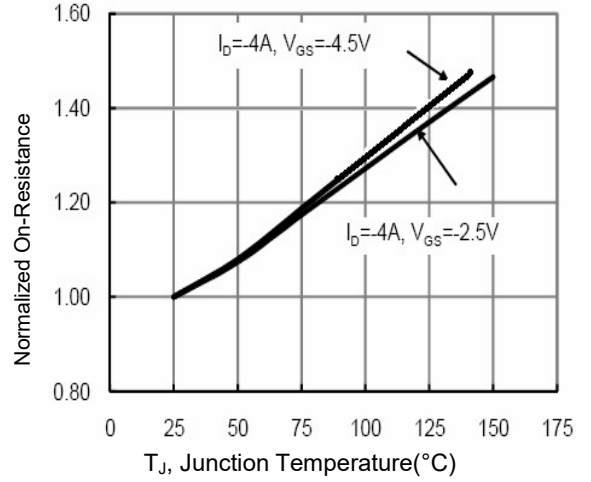


Figure 8. Rdson-Drain On-Resistance

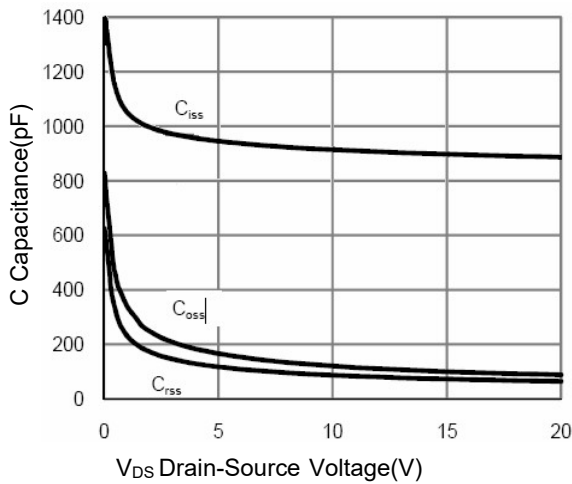


Figure 9. Capacitance vs. VDS

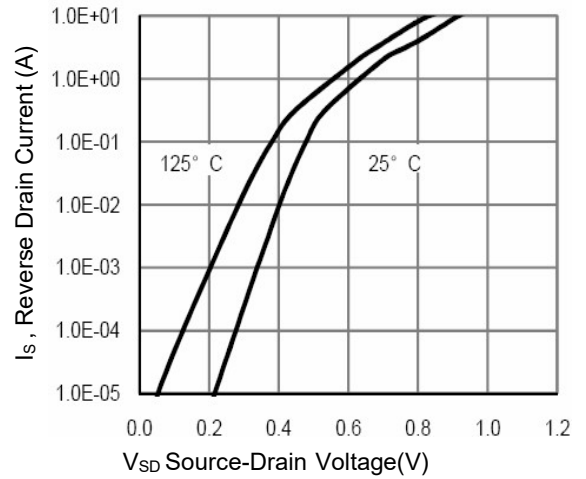


Figure 10. Source-Drain Diode Forward

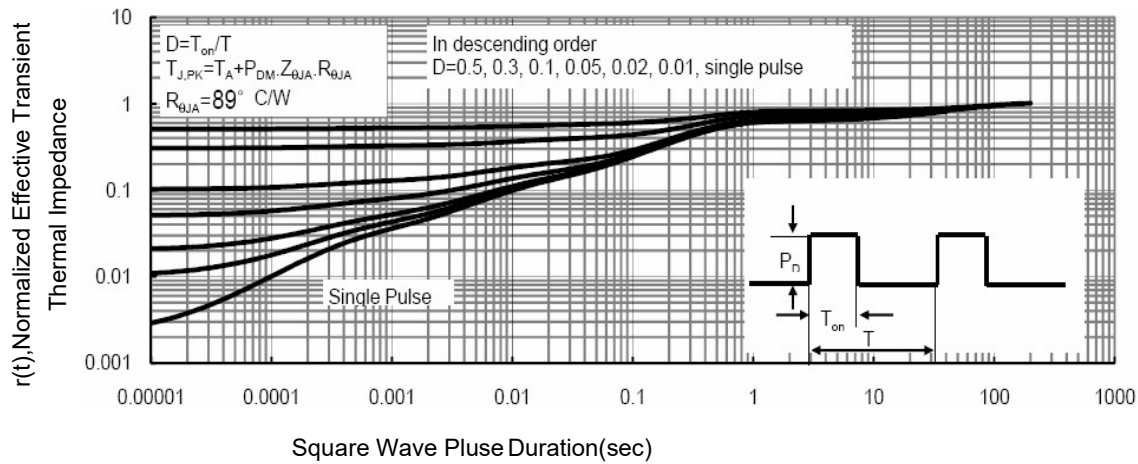


Figure 11. Normalized Maximum Transient Thermal Impedance

Typical Electrical and Thermal Characteristic Curves

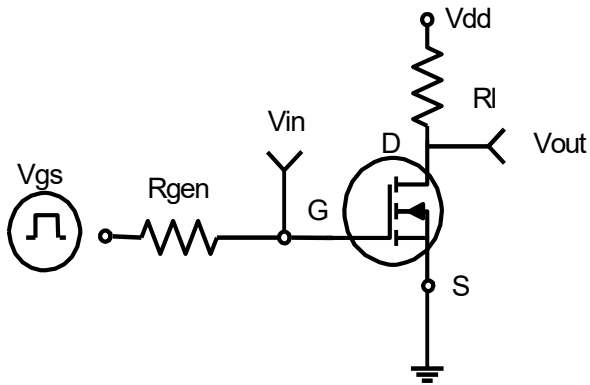


Figure 12. Switching Test Circuit

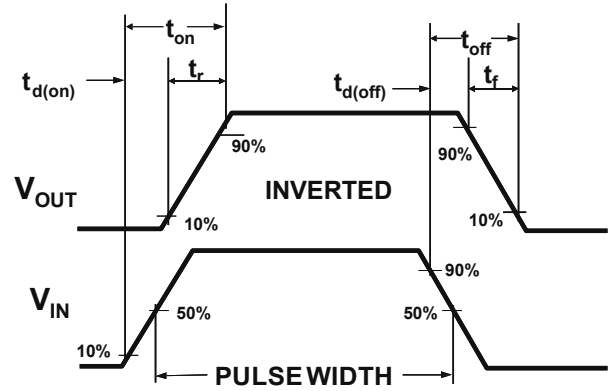
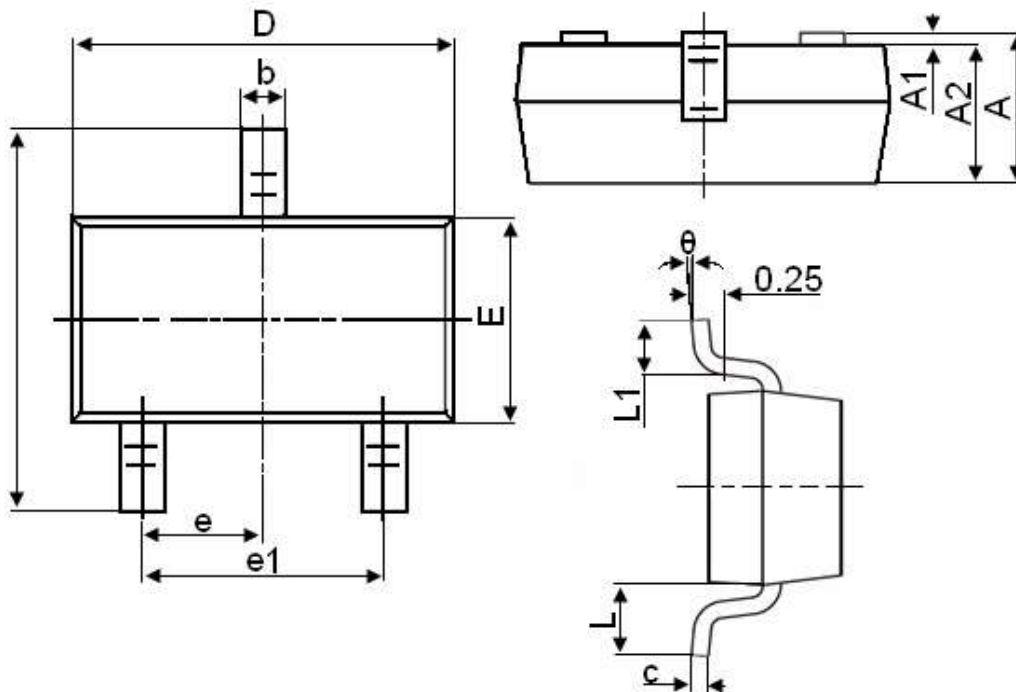


Figure 13. Switching Waveforms

Package Outline Dimensions (SOT23)



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

Notes

1. All dimensions are in millimeters.
2. Tolerance $\pm 0.10\text{mm}$ (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.